SEMICONDUCTOR DEVICE HAVING A FLAG WITH OPENING

Abstract of the Disclosure

A semiconductor device (30) utilizes a lead frame (32) having a window-frame flag (36). An opening (44) within the flag creates an interior edge (46) which is tapered, preferably to an angle ϕ that is between 55° and 65°. The tapered interior edge reduces boundary-layer separation of a resin molding compound during formation of a resin package body (42). Thus, voids in the resin packaging material near the interior edge of the flag are less likely to be formed.

FIG. 3 accompanies this abstract.